5-104071-2 - ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 5-104071-2 PCB Mount Header, Vertical, Board-to-Board, 5 Position, 1.27 mm [. 05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 5

Number of Rows: 1

Features

E T E connectivity

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	5
Number of Rows	1
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Electrical Characteristics Dielectric Withstanding Voltage (Max)	500 VAC

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Operating Voltage	30 VAC
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

Termination Features

Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
Mating Retention Type	Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.27 mm[.05 in]
Housing Material	LCP
Dimensions	

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PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
ndustry Standards	
UL Rating	Recognized
Compatible With Agency/Standards Products	CSA, UL
Compatible With Approved Standards Products	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	42
Packaging Method	Box, Tube
Other	

Product Compliance

Position Locations Omitted

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C
Product Compliance Disclaimer	

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | AMPMODU System 50



Customers Also Bought



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TE Part #GA30K5D318 PRO2-PROBE

Documents

Product Drawings

05 SYSTEM 50 HDR SRST SHRD SN

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_5-104071-2_T.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-104071-2_T.3d_igs.zip

English

Customer View Model

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ENG_CVM_CVM_5-104071-2_T.3d_stp.zip
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English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Product Specifications
Application Specification

English